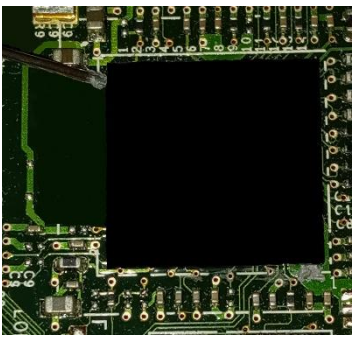




News Release

January 2021

EPOXICAST™ M21 – Epoxy Adhesive for Electronic Assemblies



epoxySet is showcasing the EPOXICAST™ M21, Low viscosity adhesive for advanced electronic assembly applications. It is designed for use as a filling epoxy in dam-and-fill encapsulations as well as underfills for CSP/BGA and Flip Chip applications. With high dielectric and insulative properties, the EC-M21 is an excellent choice for all sensitive electronics.

As a filled, halogen free system, it yields a low thermal expansion coefficient of 37ppm/°C with a high glass transition temperature of 124°C. Cure shrinkage is 0.12% and offers very good moisture resistance even in a high humidity environments.

This free flowing, one part epoxy has a 2 hour work time that will cure quickly at elevated temperatures. It is shipped frozen in 10 and 30cc syringes and has a shelf life of one year when stored at -40°C.

epoxySet is an innovative custom formulator of Epoxies, Urethanes, Silicones, Thermal Greases and UV cures for the electronic, medical, semi-conductor, optics, automotive and aerospace industries. Our extensive experience allows us to quickly modify our wide-ranging product line for any requirement. Please contact our technical support staff at 401-726-4500 or info@epoxyset.com

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